

Knowledgebase > FAQs by core architecture > Arm > What is the difference between LA-2729 and LA-3770?

## What is the difference between LA-2729 and LA-3770?

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The LA-2729 and LA-3770 are both IDC20A-to-MIPI converters, but they differ in the signal assignment of the upper 10 pins of the MIPI-20 connector.

- LA-2729: converts IDC20A to MIPI-10/20T
- LA-3770: converts IDC20A to MIPI-10/20/34

## **Key differences:**

- LA-2729 uses a MIPI-20T connector with the following pin mapping:
  - Pin 12 = TRACECLK
  - Pin 14 = TRACEDATA[0]
  - Pin 16 = TRACEDATA[1]
  - Pin 18 = TRACEDATA[2]
  - Pin 20 = TRACEDATA[3]

## Pinout MIPI-20T Connector

Signal	Pin			Pin	Signal
VREF-DEBUG	1			2	TMS TMSC SWDIO
GND	3	- 10	- 10	4	TCK TCKC SWCLK
GND	5			6	TDO - SWO
GND (KEY)	7			8	TDI
GND	9			10	RESET-
GND	11			12	TRACECLK
GND	13	<b>III</b>		14	TRACEDATA[0]
GND	15			16	TRACEDATA[1]
GND	17			18	TRACEDATA[2]
GND	19		<b>III</b>	20	TRACEDATA[3]

Note

This converter does not connect the trace pins of a CoreSight MIPI20T connector since they are not used by IDC20A debug cables. Whereas tracing via SWO/SWV is supported.

- LA-3770 uses a MIPI-20D connector with the following pin mapping:
  - o Pin 12 = RTCK
  - o Pin 14 = TRST-PULLDOWN
  - Pin 16 = TRST-
  - $\circ$  Pin 18 = EDBGRQ (EMU0)
  - Pin 20 = DBGACK (EMU1)



Signal	Pin			Pin	Signal
VREF-DEBUG	1			2	TMS TMSC SWDIO
GND	3	i.	a a	4	TCK TCKC SWCLK
GND	5		<b>II</b>	6	TDO - SWO
GND (KEY)	7			8	TDI
GND	9		<b>II</b>	10	RESET-
GND	11			12	RTCK
GND	13			14	TRST- PULLDOWN
GND	15			16	TRST-
GND	17		<b>II</b>	18	EDBGRQ (EMU0)
GND	19			20	DBGACK (EMU1)

## Notes

- Most evaluation boards use a MIPI-20T pinout.
- $\bullet\,$  LA-3770 can be reconfigured (solder bridges) for MIPI-20T.

For further details, refer to the  $\underline{\text{Arm Debug and Trace Interface Specification}}.$